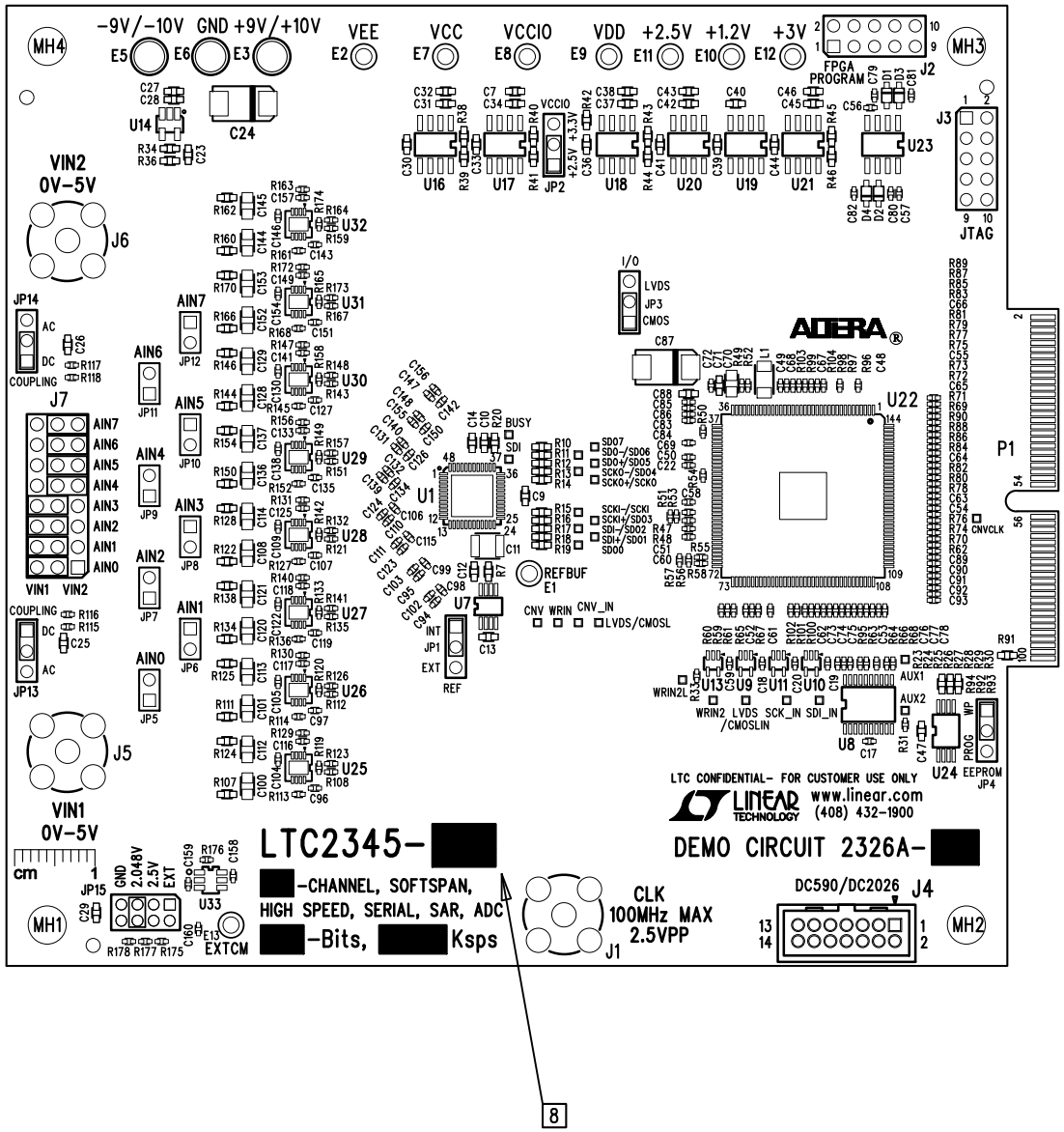
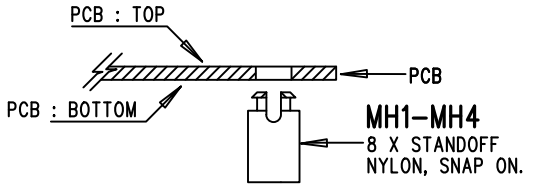
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	1	1ST PROTOTYPE	GUY H.	12–18–14



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC–A–610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE–OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



8. MARK EACH ASSEMBLY TYPE, SUFFIX, NUMBER OF –BIT, KSPS RATE, AND –CHANNEL IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY TYPE	U1	SUFFIX	–BIT	Ksps
A	LTC2345–18	45–18	18	200
B	LTC2345–16	45–16	16	200

APPROVALS	
PCB DES.	KIM T.
APP ENG.	GUY H.
SCALE = NONE	

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TITLE: TOP ASSEMBLY DRAWING
8–CHANNEL, SOFTSPAN, HIGH SPEED, SERIAL, SAR, ADC

SIZE	IC NO.	REV.
N/A	LTC2345IUK FAMILY DEMO CIRCUIT 2326A	1

FILENAME: DC2326A–1.PCB SHT 1 OF 2